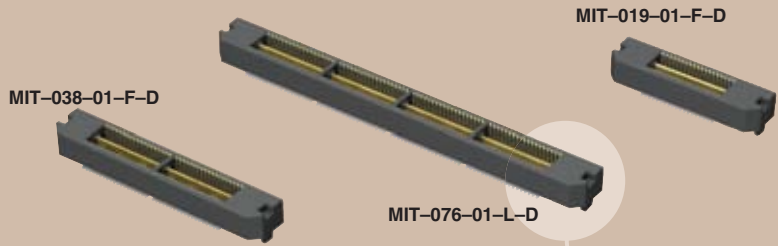




(0,635mm) .025"

MIT SERIES



# THROUGH-HOLE GROUND PLANE HEADER

## SPECIFICATIONS

For complete specifications and recommended PCB layouts see [www.samtec.com?MIT](http://www.samtec.com?MIT)

**Insulator Material:**

Liquid Crystal Polymer



**Contact Material:**

Phosphor Bronze

**Plating:**

Au or Sn over 50µ" (1,27µm) Ni

**Current Rating:**

Contacts: 1.6A @ 80°C

Ground Plane: 8.7A @ 80°C

**Operating Temp Range:**

-55°C to +125°C

**Voltage Rating:**

275 VAC

**Max Cycles:**

100

**RoHS Compliant:**

Yes

**Processing:**

Lead-Free Solderable:

Yes

**SMT Lead Coplanarity:**

(0,10mm) .004" max (019-076)

**Board Stacking:**

For applications requiring more than two connectors per board or 76 positions or higher, contact [ipg@samtec.com](mailto:ipg@samtec.com)

**Board Mates:**  
MIS

**Cable Mates:**  
MICD

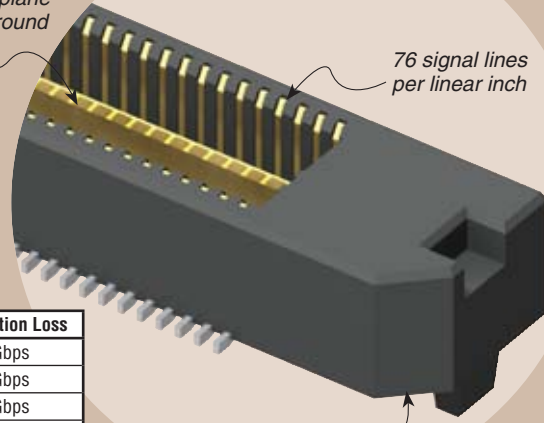


• Mixed technology footprint

Integral metal plane for power or ground

76 signal lines per linear inch

Choice of mated heights



Polarized

**ALSO AVAILABLE**

Board Spacing Standoffs. See SO Series.

5mm Stack Height	Type	Rated @ 3dB Insertion Loss
Single-Ended Signaling	-D	8.5 GHz / 17 Gbps
Differential Pair Signaling	-D	8.5 GHz / 17 Gbps
Differential Pair Signaling	-DP	9.5 GHz / 19 Gbps

Performance data for other stack heights and complete test data available at [www.samtec.com?MIT](http://www.samtec.com?MIT) or contact [sig@samtec.com](mailto:sig@samtec.com)

## APPLICATION SPECIFIC OPTION

- 11mm, 16mm, 18,75mm and 22mm stack height
  - 30µ" (0,76µm) Gold
  - Differential Pair and "Partitionable" (combine differential & single-ended banks in same connector) available.
  - 95, 114 and 133 positions per row
  - Edge Mount
- Call Samtec.



-019, -038, -057, -076  
(38 total positions per bank)

Specify LEAD STYLE from chart

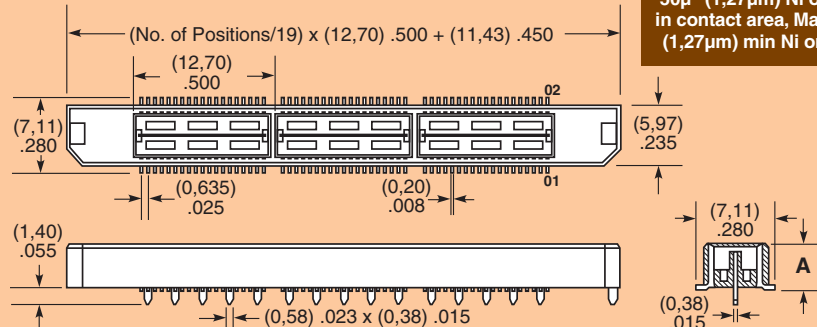
-F  
= Gold Flash on Signal Pins and Ground Plane, Matte Tin on tails

-L  
= 10µ" (0,25µm) Gold on Signal Pins and Ground Plane, Matte Tin on tails

-C\*  
= Electro-Polished Selective 50µ" (1,27µm) min Au over 150µ" (3,81µm) Ni on Signal Pins in contact area, 10µ" (0,25µm) min Au over 50µ" (1,27µm) Ni on Ground Plane in contact area, Matte Tin over 50µ" (1,27µm) min Ni on all solder tails

-K  
= (7,00mm) .275" DIA Polyimide film Pick & Place Pad

-TR  
= Tape & Reel



LEAD STYLE	A	MATED HEIGHT
-01	(4,27) .168	(5,00) .197
-02	(7,26) .286	(8,00) .315

Processing conditions will affect mated height.

Note: Rugged through-hole ground plane soldered to board (requires paste-over-hole, not press fit) for added retention to PCB.

Due to technical progress, all designs, specifications and components are subject to change without notice.

[WWW.SAMTEC.COM](http://WWW.SAMTEC.COM)